orney Docket No.: MP0115



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

flicant: Sehat Sutardia

Art Unit: 2826

erial No.: 09/966,914

Examiner: Alexander Williams

Filed

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: September 27, 2001

Title

: IMPROVED INTEGRATED CHIP PACKAGE HAVING INTERMEDIATE

SUBSTRATE

Commissioner for Patents Washington, D.C. 20231

REQUEST FOR CORRECTION OF FORM PTO-892

Applicant submits that in the 7/31/02 Office Action the Examiner cited US Patent No. 5,311,402 (Kobayashi), but did not include the Kobayashi reference on the PTO-892 form. respectfully requests that the Examiner list the Kobayashi reference on the PTO-892 form, initial the entry to indicate that the reference has been cited, and send to Applicant a revised version of form PTO-892.

Respectfully submitted,

Joseph /L. Stevenson

Req. No. 43,163

Please address all correspondence to:

Eric B. Janofsky

General Patent Counsel

Marvell Semiconductor, Inc.

700 First Avenue, Mail Stop 509

Sunnyvale, CA 94089

General Telephone Number (408) 222-2500

Facsimile (408) 752-9034

Customer No. 23624

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

January 16, 2003

Date of Deposit

Signature

Joseph L Stevenson

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